

# LM66100 入力極性保護機能搭載、5.5V、1.5A、79mΩ、低静止電流 (I<sub>Q</sub>) の理想的なダイオード

## 1 特長

- 広い動作電圧範囲：1.5V～5.5V
- VIN の逆電圧スタンドオフ：  
絶対最大定格 -6V
- 最大連続電流 (I<sub>MAX</sub>): 1.5A
- オン抵抗 (R<sub>ON</sub>)
  - 5V V<sub>IN</sub> = 79mΩ (標準値)
  - 3.6V V<sub>IN</sub> = 91mΩ (標準値)
  - 1.8V V<sub>IN</sub> = 141mΩ (標準値)
- コンパレータのチップ・イネーブル ( $\overline{CE}$ )
- チャネルのステータス表示 (ST)
- 低消費電流
  - 3.6V V<sub>IN</sub> 時のシャットダウン電流 (I<sub>SD,VIN</sub>): 120nA (標準値)
  - 3.6V V<sub>IN</sub> 時の静止電流 (I<sub>Q, VIN</sub>): 150nA (標準値)

## 2 アプリケーション

- スマート・メーター
- ビルディング・オートメーション
- GPS およびトラッキング
- プライマリおよびバックアップ・バッテリー

## 3 概要

LM66100 は、各種アプリケーションに適した単一入力、単一出力 (SISO) の集積化理想ダイオードです。このデバイスは、1.5V～5.5V の入力電圧範囲で動作でき、最大 1.5A の連続電流をサポートできる P チャネル MOSFET を内蔵しています。

チップ・イネーブルは、 $\overline{CE}$  ピンの電圧を入力電圧と比較することで動作します。 $\overline{CE}$  ピンの電圧が VIN より高い場合、デバイスはディセーブルで、MOSFET はオフです。 $\overline{CE}$  ピンの電圧の方が低い場合、MOSFET はオンです。LM66100 には逆極性保護 (RPP) 機能もあり、バッテリーの逆接続など入力の誤配線からデバイスを保護します。

デュアル・ダイオードの OR 実装のように、2 つの LM66100 を OR 構成で使用することもできます。この構成では、極めて高い入力電圧を出力に伝達しながら、逆電流が入力電源に流れ込むのを阻止できます。これらのデバイスは内部電圧コンパレータで入力と出力の電圧を比較し、逆電流がブロックされるようにします。

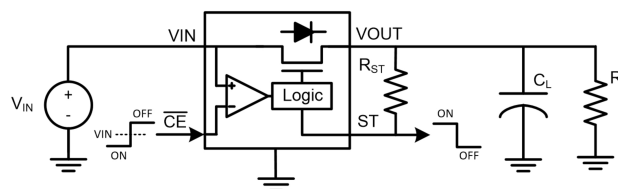
LM66100 は標準の SC-70 パッケージで供給され、-40°C～125°C の接合部温度範囲で仕様が規定されています。

### 製品情報<sup>(1)</sup>

型番	パッケージ	本体サイズ (公称)
LM66100	SC-70 (6)	2.1mmx2.0mm

(1) 提供されているすべてのパッケージについては、巻末の注文情報を参照してください。

### 代表的なアプリケーション



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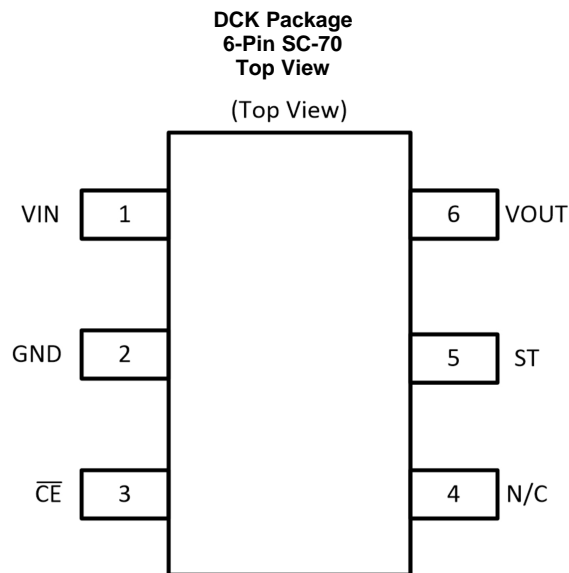
## 4 改訂履歴

2019年3月発行のものから更新

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## 5 Pin Configuration and Functions



**Pin Functions**

PIN		I/O	DESCRIPTION
NO.	NAME		
1	VIN	I	Device input
2	GND	-	Device ground
3	$\overline{CE}$	I	Active-low chip enable. Can be connected to VOUT for reverse current protection. Do not leave floating.
4	N/C	-	Not internally connected, can be tied to GND or left floating.
5	ST	O	Active-low open-drain output, pulled low when the chip is disabled. Hi-Z when the chip is enabled. Connect to GND if not required.
6	VOUT	O	Device output

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>IN</sub>	Maximum Input Voltage Range	-6	6	V
V <sub>OUT</sub>	Maximum Output Voltage Range	-0.3	6	V
V <sub>CE</sub>	Maximum $\overline{\text{CE}}$ Pin Voltage	-0.3	6	V
V <sub>ST</sub>	Maximum ST Pin Voltage	-0.3	6	V
I <sub>SW, MAX</sub>	Maximum Continuous Switch Current		1.5	A
I <sub>SW, PLS</sub>	Maximum Pulsed Switch Current ( $\leq 120$ ms, 2% Duty Cycle)		2.5	A
I <sub>D, PLS</sub>	Maximum Pulsed Body Diode Current ( $\leq 0.1$ ms, 0.2% Duty Cycle)		2.5	A
I <sub>CE</sub>	Maximum $\overline{\text{CE}}$ Pin Current	-1		mA
I <sub>ST</sub>	Maximum ST Pin Current	-1		mA
T <sub>J</sub>	Junction temperature	-40	125	°C
T <sub>STG</sub>	Storage temperature	-65	150	°C
T <sub>LEAD</sub>	Maximum Lead Temperature (10 s soldering time)		300	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, allpins <sup>(1)</sup>	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less is possible with the necessary precautions. Pins listed may actually have higher performance.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	TYP	MAX	UNIT
V <sub>IN</sub>	Input Voltage Range	1.5		5.5	V
V <sub>OUT</sub>	Output Voltage Range	1		5.5	V
V <sub>CE</sub>	$\overline{\text{CE}}$ Pin Voltage Range	0		5.5	V
V <sub>ST</sub>	ST Pin Voltage Range	0		5.5	V

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		LM66100	UNIT
		DCK (SC-70)	
		6 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	192	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	124	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	52	°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	34	°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	52	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

Typical values are at 25°C with an input voltage of 3.6V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
<b>Input Supply (VIN)</b>								
$I_{SD,VIN}$	VIN Shutdown Current	VOUT = VIN VCE > VIN + 80mV IOUT = 0 A (VOUT = open)	25°C	0.12	0.3		μA	
			-40°C to 105°C			0.3	μA	
$I_{Q,VIN}$	VIN Quiescent Current	VOUT = VIN VCE < VIN - 250mV IOUT = 0 A (VOUT = open)	25°C	0.15	0.3		μA	
			-40°C to 105°C			0.3	μA	
$I_{OUT, OFF}$	OUT to IN Leakage Current (Current out of VIN)	VOUT - VIN ≤ 5.5 V VCE > VIN + 80mV	25°C	0.2	0.5		μA	
			-40°C to 85°C			2.7	μA	
			-40°C to 105°C			8	μA	
		VOUT - VIN ≤ 4.5 V VCE > VIN + 80mV	-40°C to 85°C			1.7	μA	
			-40°C to 105°C			5.1	μA	
			-40°C to 85°C			0.7	μA	
-40°C to 105°C			2.1	μA				
<b>ON-Resistance (RON)</b>								
$R_{ON}$	ON-State Resistance	IOUT = -200 mA	VIN = 5 V	25°C	79	95	mΩ	
				-40°C to 85°C				110
				-40°C to 125°C				120
$R_{ON}$	ON-State Resistance	IOUT = -200 mA	VIN = 3.6 V	25°C	91	110	mΩ	
				-40°C to 85°C				125
				-40°C to 125°C				140
$R_{ON}$	ON-State Resistance	IOUT = -200 mA	VIN = 1.8 V	25°C	141	180	mΩ	
				-40°C to 85°C				210
				-40°C to 125°C				230
<b>Comparator Chip Enable (CE)</b>								
$V_{ON}$	Turn ON Threshold	VCE - VIN	-40°C to 125°C	-250	-150	-80	mV	
$V_{OFF}$	Turn OFF Threshold	VCE - VIN	-40°C to 125°C	0	35	80	mV	
$I_{CE}$	CE Pin Leakage Current	VCE < VIN - 250mV	-40°C to 125°C	0	160	300	nA	
$I_{CE}$	CE Pin Leakage Current	VCE > VIN + 80mV	-40°C to 125°C	0	400	610	nA	
<b>Reverse Current Blocking (RCB) and Body Diode Characteristics</b>								
$I_{RCB}$	Reverse Activation Current	VCE = VOUT	-40°C to 125°C	0.5	1		A	
$V_{FWD}$	Body Diode Forward Voltage	IOUT = 10 mA VCE > VIN + 80mV	-40°C to 125°C	0.1	0.5	1.1	V	
<b>Status Indication (ST)</b>								
$V_{OL, ST}$	Output Low Voltage	IST = 1 mA	-40°C to 125°C			0.1	V	
$t_{ST}$	Status Delay Time	VCE transitions from low to high	-40°C to 125°C		1		μs	
$I_{ST}$	ST Pin Leakage Current	VCE < VIN - 250mV	-40°C to 125°C	-20		20	nA	

## 6.6 Switching Characteristics

Unless otherwise noted, the typical characteristics in the following table applies over the entire recommended operating voltage at an ambient temperature of 25°C and a load of  $C_L = 100$  nF and  $R_L = 1$  kΩ

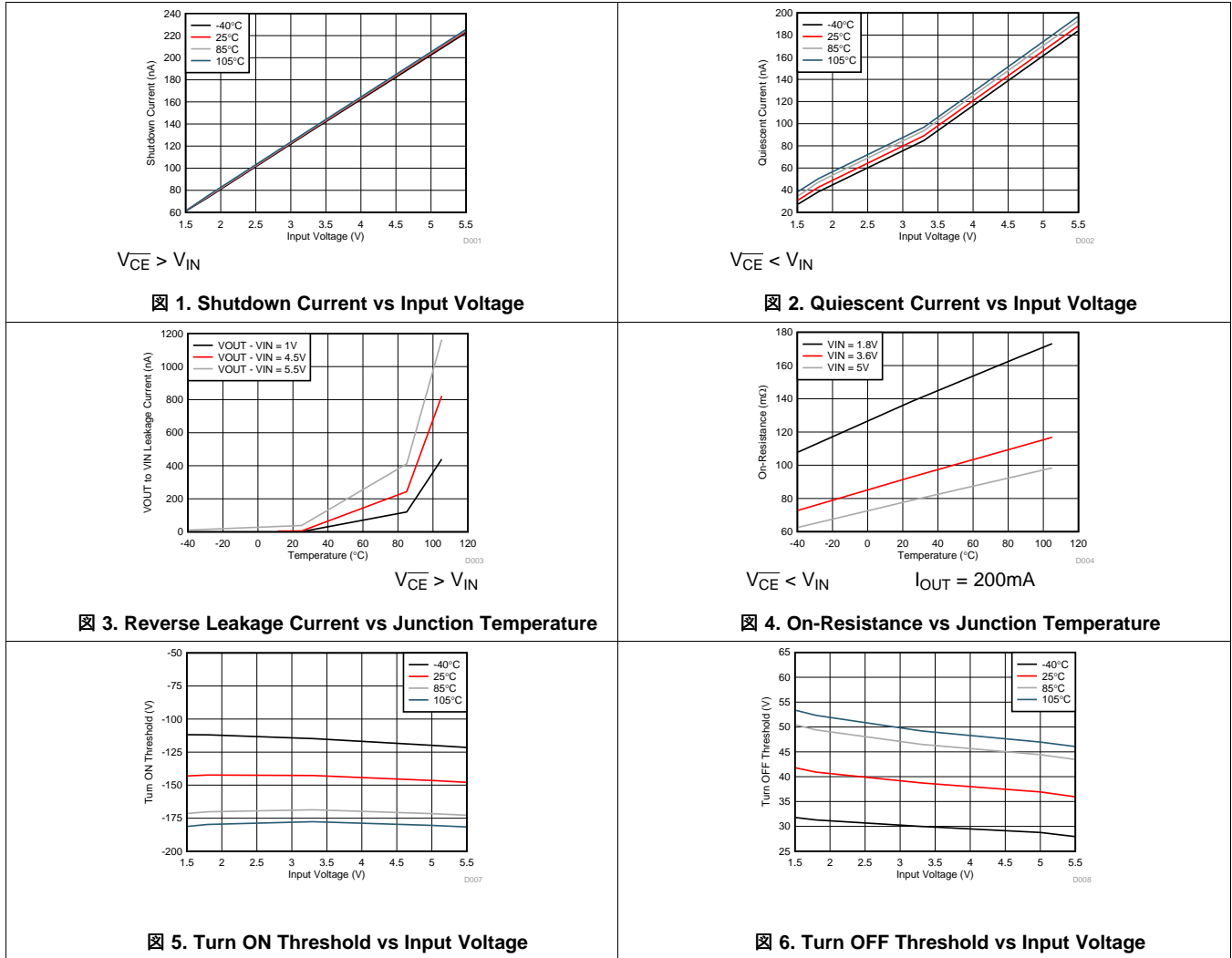
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{ON}$	Turn ON Time	VIN = 1.8 V			90		μs
		VIN = 3.6 V			40		μs
		VIN = 5 V			27		μs
$t_{OFF}$	Turn OFF Time	VIN = 1.8 V			2		μs
		VIN = 3.6 V			2		μs
		VIN = 5 V			2		μs

### Switching Characteristics (continued)

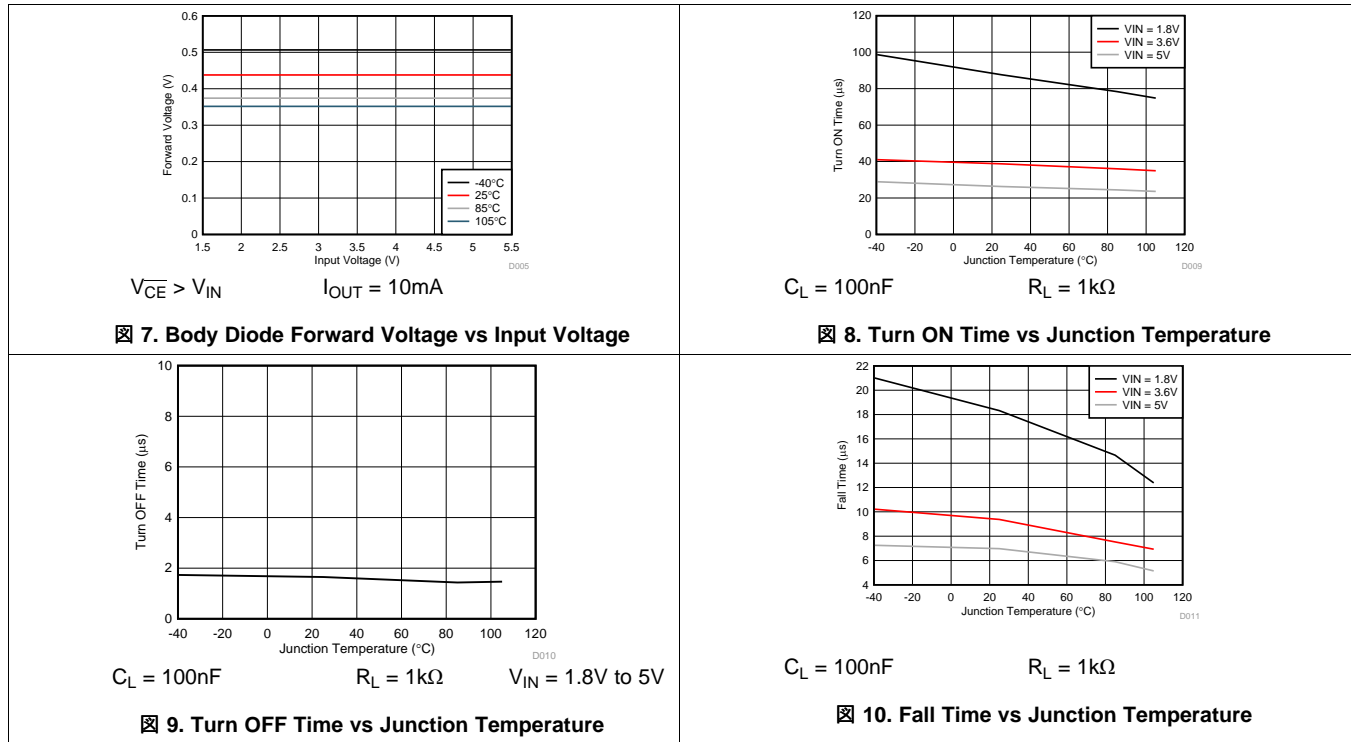
Unless otherwise noted, the typical characteristics in the following table applies over the entire recommended operating voltage at an ambient temperature of 25°C and a load of  $C_L = 100$  nF and  $R_L = 1$  k $\Omega$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{FALL}$	Output Fall Time	$V_{IN} = 1.8$ V	20		$\mu$ s
		$V_{IN} = 3.6$ V	10		$\mu$ s
		$V_{IN} = 5$ V	7.5		$\mu$ s

### 6.7 Typical Characteristics



Typical Characteristics (continued)



7 Parameter Measurement Information

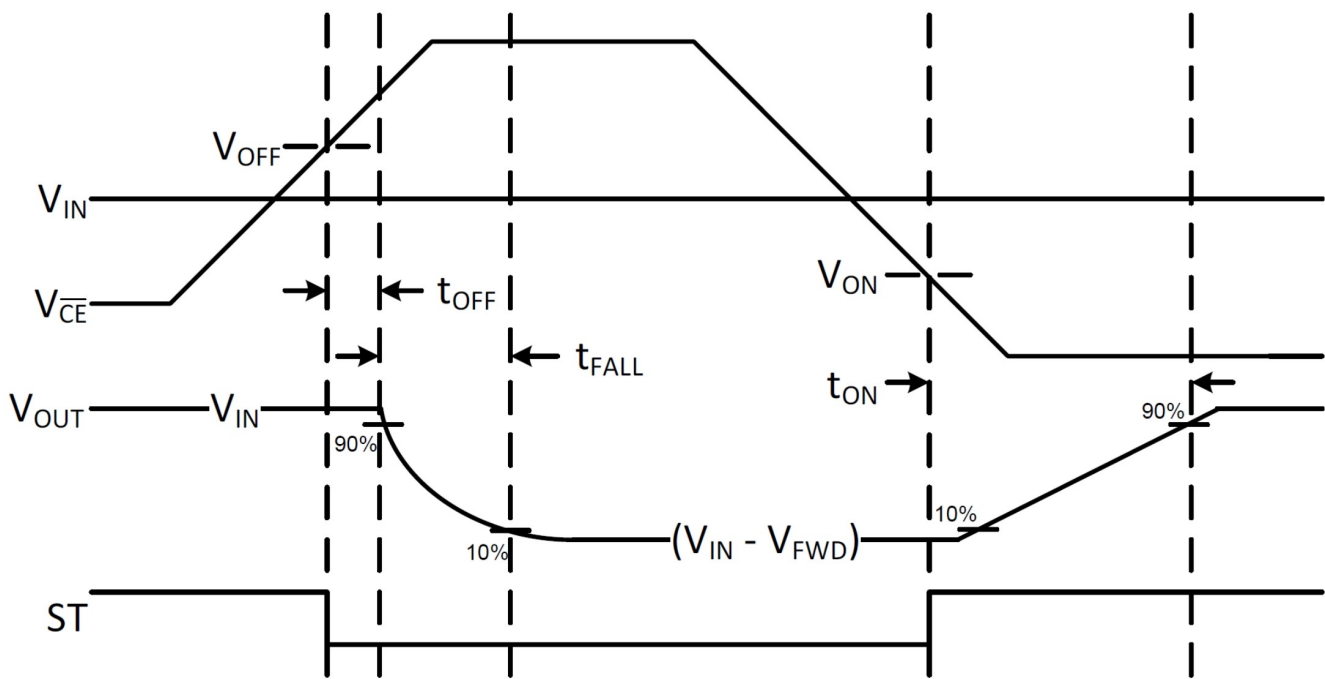


Fig 11. Timing Diagram

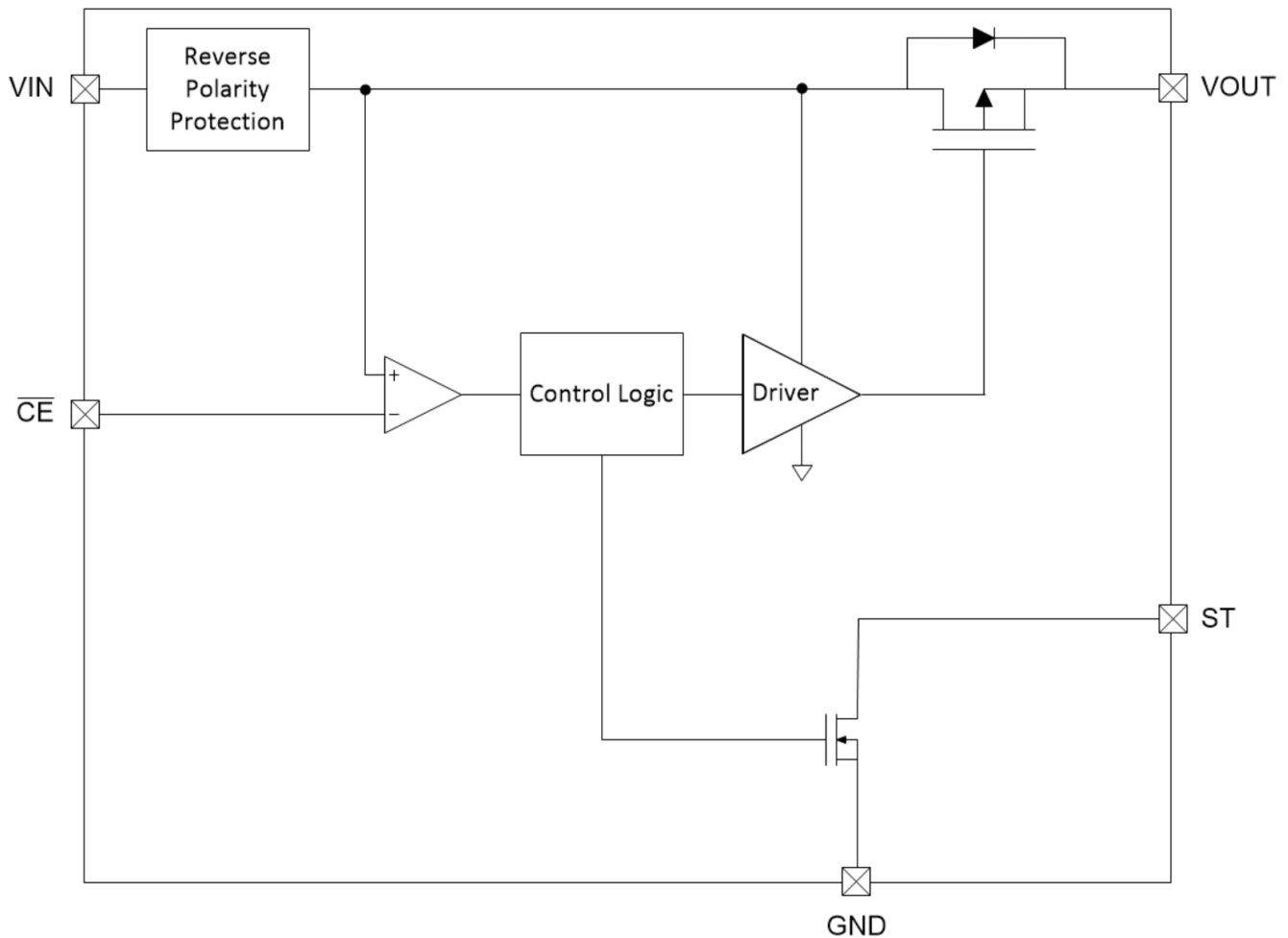
## 8 Detailed Description

### 8.1 Overview

The LM66100 is a Single-Input, Single-Output (SISO) integrated ideal diode that is well suited for a variety of applications. The device contains a P-channel MOSFET that can operate over an input voltage range of 1.5 V to 5.5 V and can support a maximum continuous current of 1.5 A.

The chip enable works by comparing the  $\overline{CE}$  pin voltage to the input voltage. When the  $\overline{CE}$  pin voltage is higher than  $V_{IN}$  by 80 mV, the device is disabled and the MOSFET is off. When the  $\overline{CE}$  pin voltage is lower than  $V_{IN}$  by 250 mV, the MOSFET is on. The LM66100 also comes with reverse polarity protection (RPP) that can protect the device from a miswired input, such as a reversed battery.

### 8.2 Functional Block Diagram





### 8.3 Feature Description

#### 8.3.1 Reverse Polarity Protection (RPP)

In the event a negative input voltage is applied, the ideal diode will stay off and prevent current flow to protect the system load. For a stand-alone, always on application,  $\overline{CE}$  can be tied to GND so it will not go negative with respect to GND see [Figure 12](#).

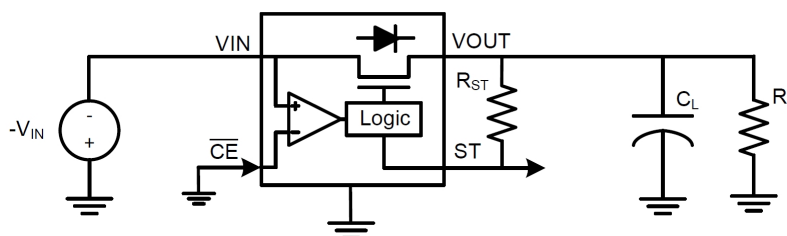


Figure 12. RPP Protection Circuit

#### 8.3.2 Always-ON Reverse Current Blocking (RCB)

By connecting the  $\overline{CE}$  pin to V\_OUT, this allows the comparator to detect reverse current flow through the switch. If the output is forced above the selected input by  $V_{OFF}$ , the channel will switch off to stop the reverse current  $I_{RCB}$  within  $t_{OFF}$ . Once the output falls to below  $V_{IN}$  by  $V_{ON}$ , the device will turn back on.

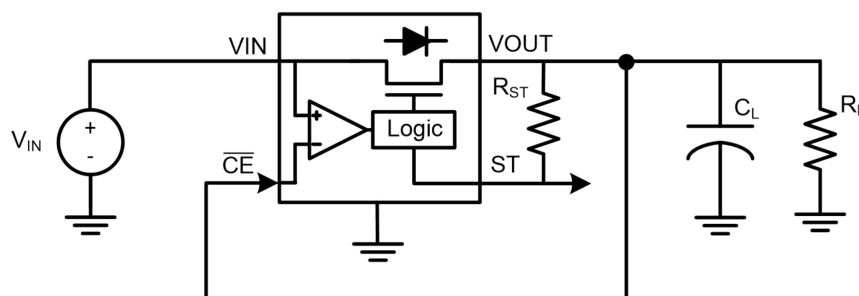


Figure 13. RCB Circuit

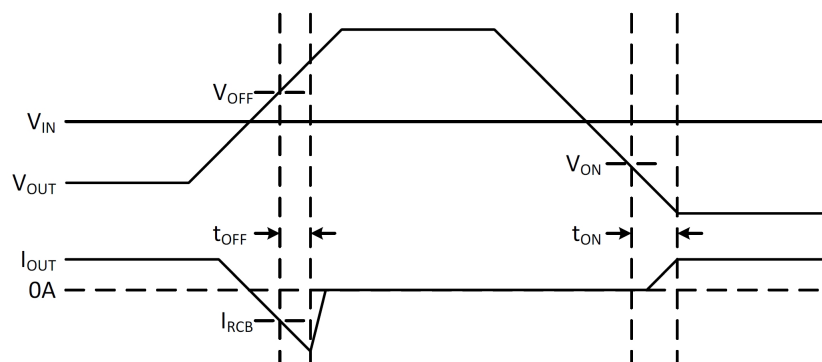


Figure 14. RCB Waveforms

### 8.4 Device Functional Modes

表 1 summarizes the Device Functional Modes:

表 1. Device Functional Modes

State	IN-to-OUT	Power Dissipation	ST State
OFF	Diode	$I_{OUT} \times V_{FWD}$	L
ON	Switch	$I_{OUT}^2 \times R_{ON}$	H

## 9 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The LM66100 Ideal Diode can be used in a variety of stand-alone and multi-channel applications.

### 9.2 Typical Applications

#### 9.2.1 Dual Ideal Diode ORing

Two LM66100 Ideal Diodes can be used together for ORing between two power supplies.

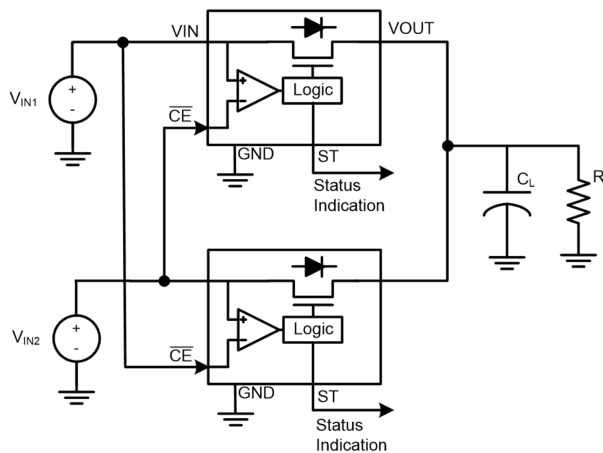


图 15. Dual Ideal Diode ORing

#### 9.2.1.1 Design Requirements

Design a circuit that allows the highest input voltage to power a downstream system while providing reverse current protection.

#### 9.2.1.2 Detailed Design Procedure

This circuit ties the  $\overline{CE}$  of each device to the opposite power source. In this configuration, the highest supply will always be selected using a make-before-break logic. This prevents any reverse current flow between the supplies and avoids the need of a dedicated reverse current blocking comparator. For ORing applications that need RPP, it is recommended to use a series resistor ( $R_{\overline{CE}}$ ) to limit the current into the  $\overline{CE}$  pin during a negative voltage event.

## Typical Applications (continued)

### 9.2.1.3 Application Curves

The below scope shot shows the output voltage (VOUT) being initially powered by VIN1. When VIN2 is applied, it powers VOUT because it is a higher voltage. When VIN2 is removed, VOUT is once again powered by VIN1.

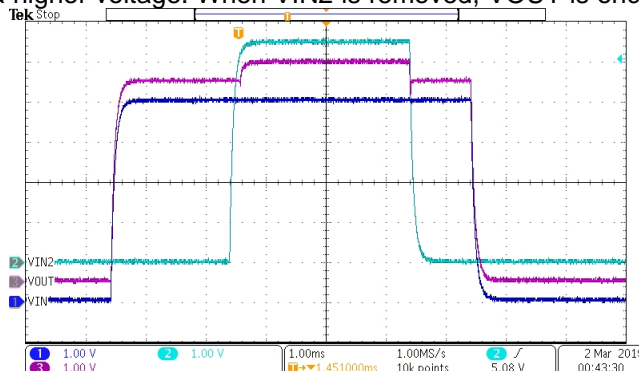


Figure 16. Dual Ideal Diode ORing Behavior

## 9.2.2 Dual Ideal Diode ORing for Continuous Output Power

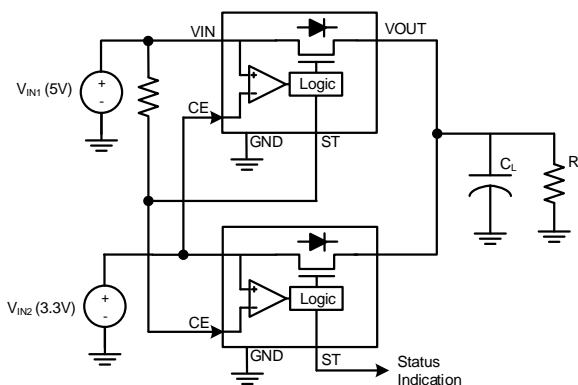


Figure 17. Dual Ideal Diode ORing for Continuous Output Power

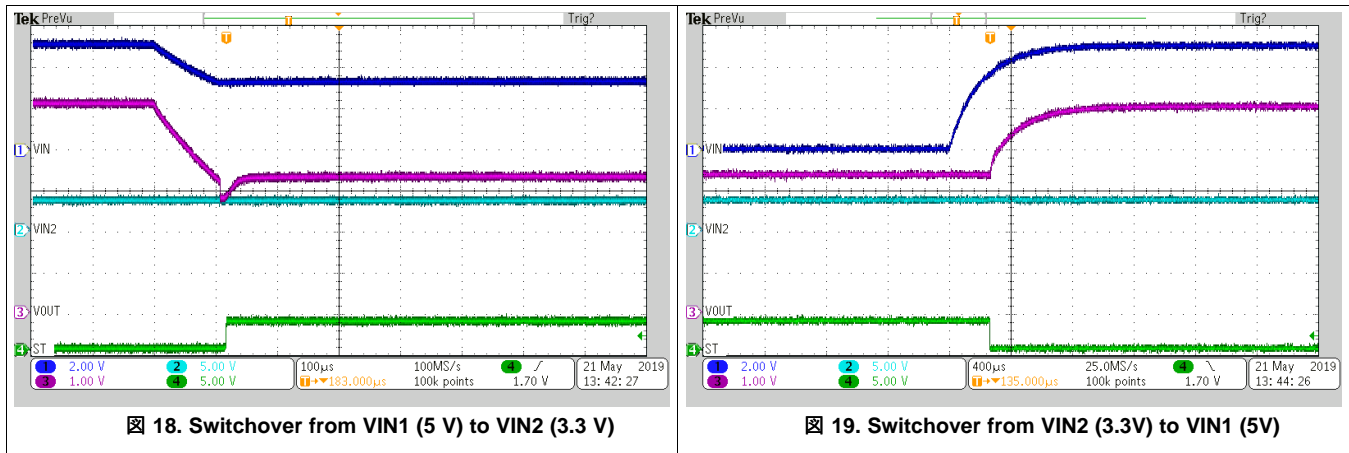
### 9.2.2.1 Design Requirements

The shortcoming of the previous implementation happens when both input voltages are the same for a long period of time, then both devices will completely turn off, powering down the output load. To avoid this case, the status output from the priority supply and a pull up resistor can be used causing both devices to switchover at the same time. For ORing applications that need RPP, it is recommended to use a series resistor ( $R_{CE}$ ) to limit the current into the CE pin during a negative voltage event.

## Typical Applications (continued)

### 9.2.2.2 Application Curves

The figures below show the switchover performance between VIN1 and VIN2.



### 9.2.3 ORing with Discrete MOSFET

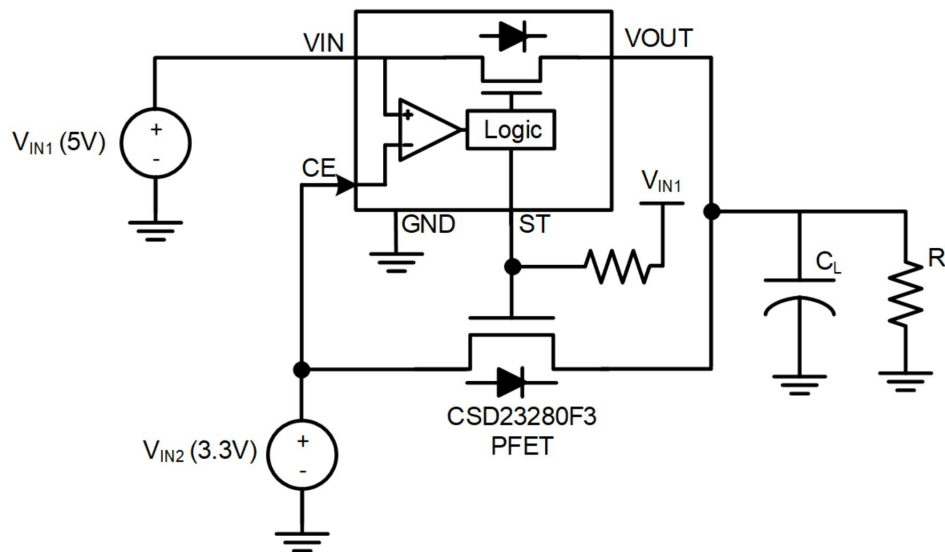


Figure 20. ORing with a Discrete MOSFET

#### 9.2.3.1 Design Requirements

Similar to the Dual Ideal Diode circuit, the Status Output can also be used to control a discrete P-Channel MOSFET. This can be useful in applications that want to minimize the leakage current on the secondary supply, such as battery backup systems. This configuration can also be used on systems that require a lower RON on the secondary rail, useful for higher current applications.

When the Ideal Diode path is enabled, the status will be Hi-Z and pull up the gate of the external PFET to keep it off. When the main supply (VIN1) drops such that backup supply (VIN2) is higher than VIN1, the ideal diode will be disabled and pull the ST pin and the PFET gate low to turn on the discrete MOSFET path.

## Typical Applications (continued)

### 9.2.3.2 Application Curves

The figures below show the switchover performance between VIN1 and VIN2.

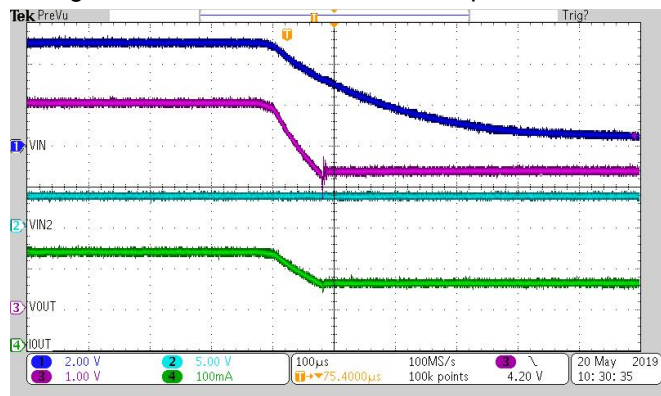


Figure 21. Switchover from VIN1 5 V to VIN2 3.3 V

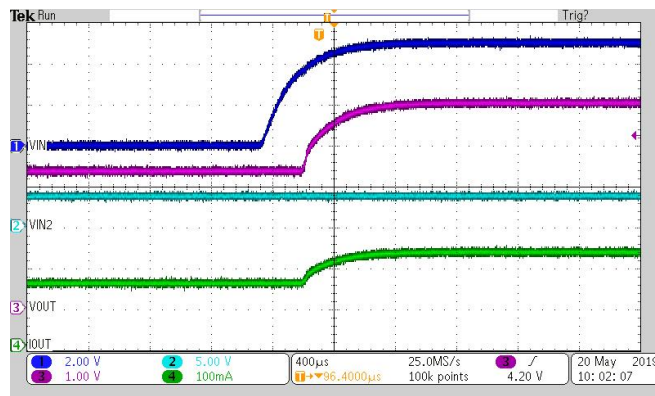


Figure 22. Switchover from VIN2 3.3 V to VIN1 5 V

## 10 Power Supply Recommendations

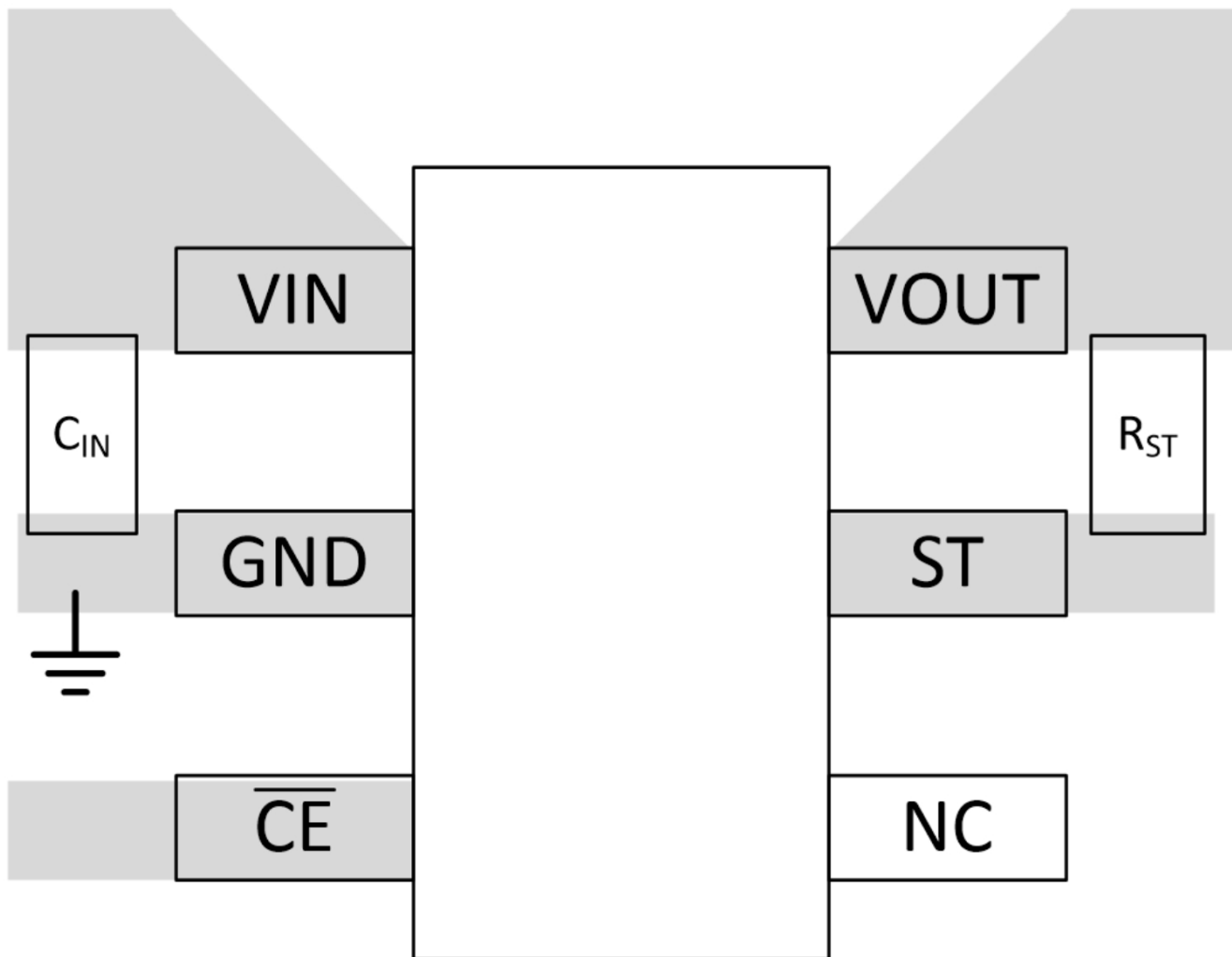
The device is designed to operate with a VIN range of 1.5 V to 5.5 V. The VIN power supply must be well regulated and placed as close to the device terminal as possible. The power supply must be able to withstand all transient load current steps. In most situations, using an input capacitance (CIN) of 1 µF is sufficient to prevent the supply voltage from dipping when the switch is turned on. In cases where the power supply is slow to respond to a large transient current or large load current step, additional bulk capacitance may be required on the input.

## 11 Layout

### 11.1 Layout Guidelines

For best performance, all traces must be as short as possible. To be most effective, the input and output capacitors must be placed close to the device to minimize the effects that parasitic trace inductances may have on normal operation. Using wide traces for VIN, VOUT and GND helps minimize the parasitic electrical effects.

### 11.2 Layout Example



☒ 23. LM66100 Layout Example

## 12 デバイスおよびドキュメントのサポート

### 12.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](http://ti.com)のデバイス製品フォルダを開いてください。右上の「アラートを受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

### 12.2 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](http://e2e.ti.com), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.3 商標

E2E is a trademark of Texas Instruments.

### 12.4 静電気放電に関する注意事項



すべての集積回路は、適切なESD保護方法を用いて、取扱いと保存を行うようにして下さい。

静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

### 12.5 Glossary

**SLYZ022** — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">LM66100DCKR</a>	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1CU
LM66100DCKR.A	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1CU
<a href="#">LM66100DCKT</a>	Active	Production	SC70 (DCK)   6	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 105	1CU
LM66100DCKT.A	Active	Production	SC70 (DCK)   6	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 105	1CU

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF LM66100 :**



- Automotive : [LM66100-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM66100DCKR	SC70	DCK	6	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3
LM66100DCKR	SC70	DCK	6	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LM66100DCKT	SC70	DCK	6	250	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM66100DCKR	SC70	DCK	6	3000	210.0	185.0	35.0
LM66100DCKR	SC70	DCK	6	3000	208.0	191.0	35.0
LM66100DCKT	SC70	DCK	6	250	210.0	185.0	35.0

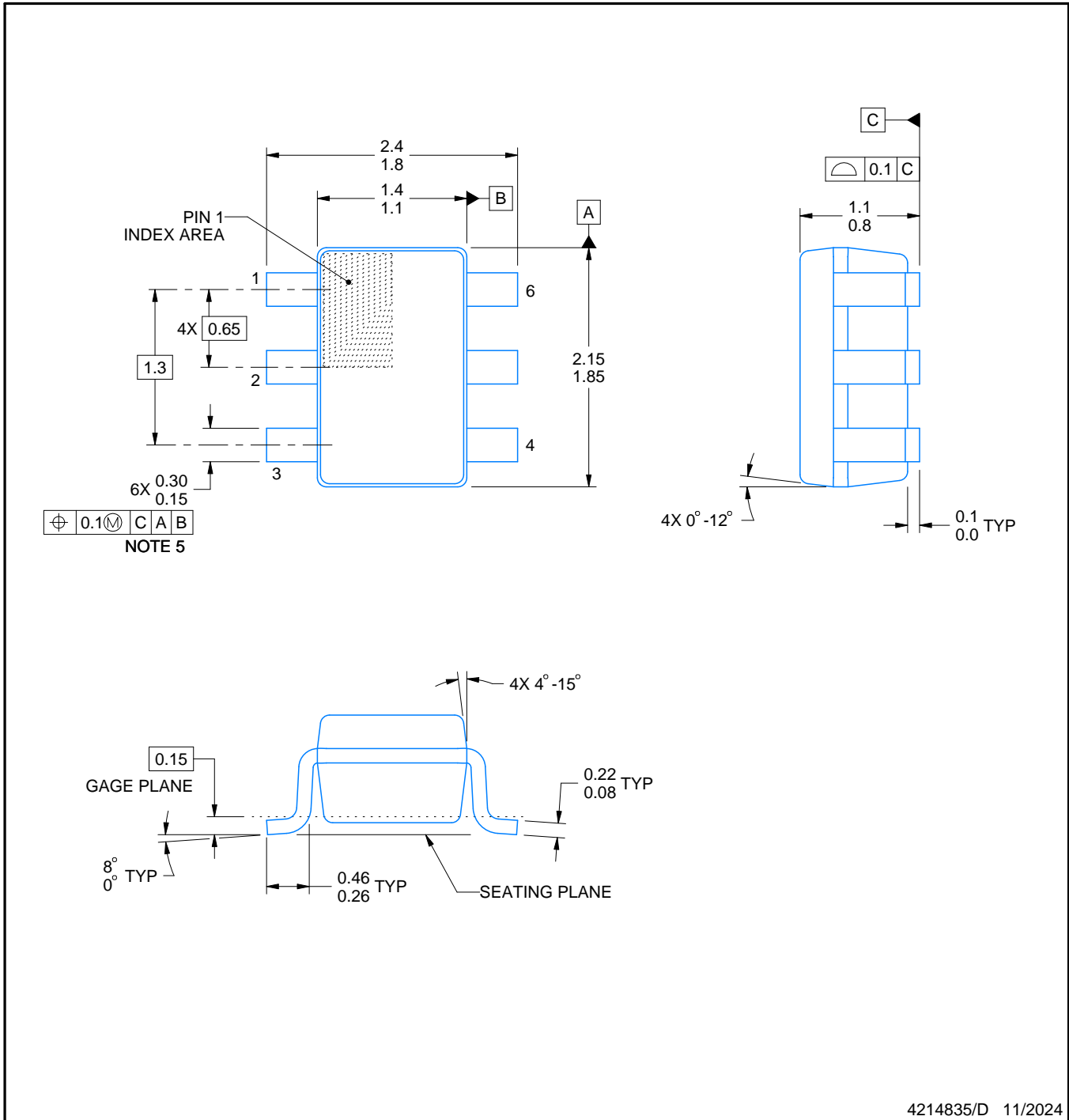
# DCK0006A



# PACKAGE OUTLINE

SOT - 1.1 max height

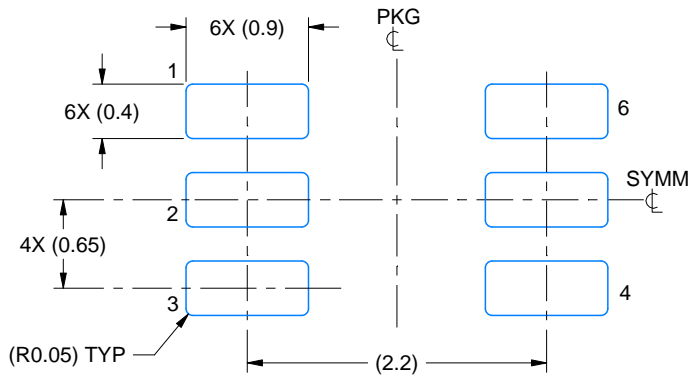
SMALL OUTLINE TRANSISTOR



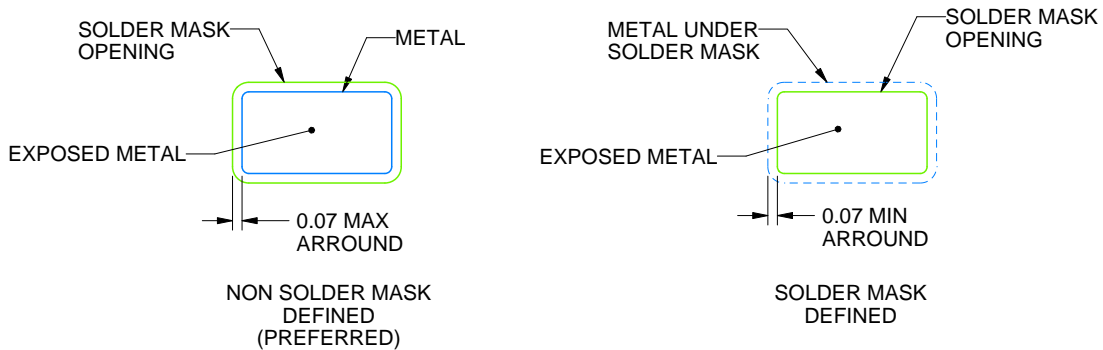
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**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
4. Falls within JEDEC MO-203 variation AB.



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X

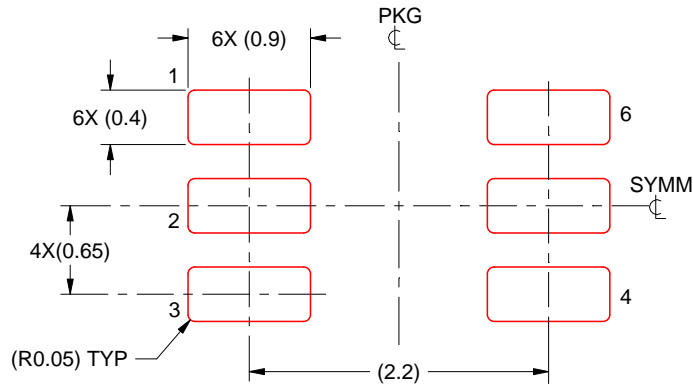


SOLDER MASK DETAILS

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NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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